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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/676,208	10/01/2003	Mei Wen	007135/CMP/ECP 7685	
DUGAN & DUGAN, PC 55 SOUTH BROADWAY TARRYTOWN, NY 10591		• *	EXAMINER	
			WONG, EDNA	
			ART UNIT	PAPER NUMBER
		·	1753	
			_	
SHORTENED STATUTOR	Y PERIOD OF RESPONSE	MAIL DATE	DELIVERY MODE	
3 MONTHS		02/27/2007	PAPER	

Please find below and/or attached an Office communication concerning this application or proceeding.

If NO period for reply is specified above, the maximum statutory period will apply and will expire 6 MONTHS from the mailing date of this communication.

		Application No.	Applicant(s)		
Office Action Summan		10/676,208	WEN ET AL.		
	Office Action Summary	Examiner	Art Unit		
	The MAILING DATE of this	Edna Wong	1753		
Period fo	The MAILING DATE of this communication app or Reply	pears on the cover sheet with the c	orrespondence address		
WHIC - Exte after - If NC - Failu Any	ORTENED STATUTORY PERIOD FOR REPLY CHEVER IS LONGER, FROM THE MAILING DAYS IN THE MAIL	ATE OF THIS COMMUNICATION 36(a). In no event, however, may a reply be tim will apply and will expire SIX (6) MONTHS from . cause the application to become ABANDONE	N. nely filed the mailing date of this communication. D. (35 U.S.C. § 133)		
Status					
1)⊠	Responsive to communication(s) filed on 02 Fe	ebruary 2007.			
2a) <u></u> ☐	This action is FINAL . 2b)⊠ This	action is non-final.			
3)	,—				
	closed in accordance with the practice under E	Ex parte Quayle, 1935 C.D. 11, 45	3 O.G. 213.		
Dispositi	ion of Claims		•		
5)□ 6)⊠ 7)□	Claim(s) 1-28 is/are pending in the application. 4a) Of the above claim(s) 5-28 is/are withdrawn Claim(s) is/are allowed. Claim(s) 1-4 is/are rejected. Claim(s) is/are objected to. Claim(s) are subject to restriction and/or	n from consideration.			
Applicati	ion Papers				
9)⊠ 10)□	The specification is objected to by the Examiner The drawing(s) filed on is/are: a) access Applicant may not request that any objection to the of Replacement drawing sheet(s) including the correction The oath or declaration is objected to by the Examiner	epted or b) objected to by the Edrawing(s) be held in abeyance. See ion is required if the drawing(s) is obj	ected to. See 37 CFR 1.121(d).		
Priority u	ınder 35 U.S.C. § 119				
 12) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f). a) All b) Some * c) None of: 1. Certified copies of the priority documents have been received. 2. Certified copies of the priority documents have been received in Application No. 3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)). * See the attached detailed Office action for a list of the certified copies not received. 					
2) 🔲 Notice 3) 🔯 Inform	t(s) e of References Cited (PTO-892) e of Draftsperson's Patent Drawing Review (PTO-948) nation Disclosure Statement(s) (PTO/SB/08) r No(s)/Mail Date October 29, 2003.	4) Interview Summary (Paper No(s)/Mail Da 5) Notice of Informal Pa 6) Other:	te		

Election/Restrictions

Applicant's election without traverse of Group I, claims 1-4, in the reply filed on February 7, 2007 is acknowledged.

The requirement is still deemed proper and is therefore made FINAL.

Accordingly, claims **5-28** are withdrawn from consideration as being directed to a non-elected invention.

Specification

The disclosure is objected to because of the following informalities: page 2, line 31, it is unclear what is meant by "no nonexistent".

Appropriate correction is required.

The lengthy specification has not been checked to the extent necessary to determine the presence of all possible minor errors. Applicant's cooperation is requested in correcting any errors of which applicant may become aware in the specification.

Claim Rejections - 35 USC § 102/103

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

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A person shall be entitled to a patent unless -

(e) the invention was described in (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effects for purposes of this subsection of an application filed in the United States only if the international application designated the United States and was published under Article 21(2) of such treaty in the English language.

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

Claims **1-3** are rejected under 35 U.S.C. 102(e) as anticipated by or, in the alternative, under 35 U.S.C. 103(a) as obvious over **Dubin et al.** (US Patent No. 7,001,641 B2).

Dubin teaches a method comprising:

- (a) providing a substrate 230 having a metal seed layer 250;
- (b) applying an agitated rinse **300** (= a wash liquid introduced at a rate of between about 0.2 liters/minute (I/m) and about 2 I/m) to the metal seed layer (= for washing away any deteriorated organic material from the surface of the seed layer **250**) [col. 5, line 63 to col. 6, line 6; and Fig. 3]; and
- (c) depositing a metal fill layer **455** (= the trench **253** is filled with the conductive material) on the rinsed metal seed layer by electrochemical deposition (= electroplating) [col. 6, lines 35-47; and Fig. 4].

The metal seed layer comprises a copper seed layer (col. 4, lines 63-67).

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The providing a substrate having a metal seed layer comprises depositing the metal seed layer on the substrate by physical vapor deposition (col. 3, lines 29-36).

Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

Claim 4 is rejected under 35 U.S.C. 103(a) as being unpatentable over **Dubin et al.** (US Patent No. 7,001,641 B2) as applied to claims 1-3 above, and further in view of **Hymes** (US Patent No. 6,423,200 B1).

Dubin is as applied above and incorporated herein.

The method of Dubin differs from the instant invention because Dubin does not disclose wherein both the applying step and the depositing step are performed in the same chamber, as recited in claim 4.

Dubin teaches that unfortunately, as the substrate is transferred, the thin and delicate seed layer is often contaminated. For example, the seed layer, primarily of metal material, may oxidize as it is exposed to air during the transfer. Additionally, contaminants with organic material may occur, for example from the person transferring the substrate (col. 1, lines 49-63).

Like Dubin, Hymes teaches a seed layer treatment. Hymes teaches that applying

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a chemical cleaning solution to the metal seed layer (col. 5, lines 1-13). A combined module 203 (= an electroplating apparatus) that allows the treating 204 (= the seed layer treatment module) and plating process 206 (= the electroplating module) to be performed in-situ and therefore, allow the plating process to occur just after the treatment of the seed layer (col. 4, lines 20-32; col. 5, lines 43-57; and Fig. 2A). This is well suited to perform the copper seed layer treatment in such a way that copper oxides are prevented from growing while wafers sit in a cassette before being electroplated with copper (col. 7, lines 8-18; and Figs. 2B and 2C).

It would have been obvious to one having ordinary skill in the art at the time the invention was made to have modified both the applying step and the depositing step described by Dubin with wherein both the applying step and the depositing step are performed in the same chamber because a combined module would have prevented copper oxides from growing on the substrate while being transferred from one treatment to another as taught by Hymes (col. 7, lines 8-18).

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Edna Wong whose telephone number is (571) 272-1349. The examiner can normally be reached on Mon-Fri 7:30 am to 4:00 pm.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Nam Nguyen can be reached on (571) 272-1342. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

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Edna Wong
Primary Examiner
Art Unit 1753

EW February 22, 2007